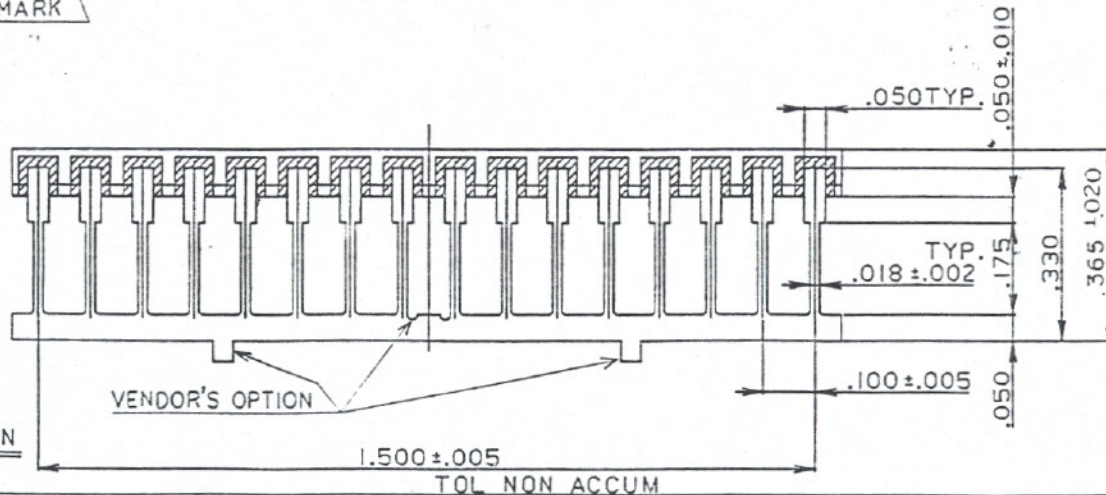
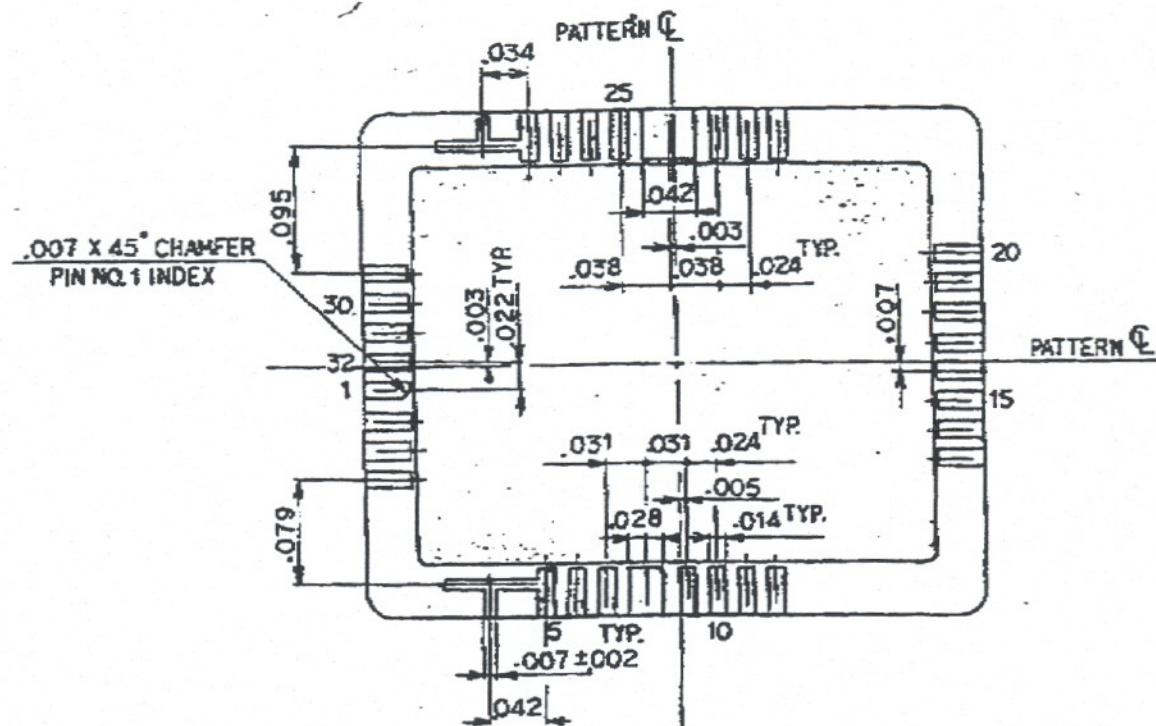


- NOTES.
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
  2. SEAL AREA TO BE METALLIZED.
  3. DIE ATTACH AREA TO BE METALLIZED.
  4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
  5. LEAD RESISTANCE : 0.25 Ω MAX. AT PIN NO. 8.24  
OTHER LESS THAN 0.5 Ω MAX.



SB032T740-1S=0  
D=0

MODIFICATION					NAME 32 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005	DRAWN K.M	CHECKED K.O	APPROVED M.M	DATE SEP.19.'87
					SCALE 4/1	MATERIAL AS INDICATED	THIRD ANGLE PROJECTION			
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-S87740		SHEET 1/2



BONDING PATTERN

					NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
					32 LEAD SIDE BRAZED PACKAGE	SEE DRAWING SPECIF.	K.M	K.O	M.M	SEP. 19 87
CHANGED	DATE	DRAWN	CHECKED	APPROVED	SCALE	MATERIAL	DATE			
					10/1		SEP. 19 87			
					KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.			SHEET
							KD-587740			3/2